



# NX3008NBKS

30 V, 350 mA dual N-channel Trench MOSFET

Rev. 1 — 1 August 2011

Product data sheet

## 1. Product profile

### 1.1 General description

Dual N-channel enhancement mode Field-Effect Transistor (FET) in a very small SOT363 (SC-88) Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

### 1.2 Features and benefits

- Very fast switching
- Low threshold voltage
- Trench MOSFET technology
- ESD protection up to 2 kV
- AEC-Q101 qualified

### 1.3 Applications

- Relay driver
- High-speed line driver
- Low-side loadswitch
- Switching circuits

### 1.4 Quick reference data

Table 1. Quick reference data

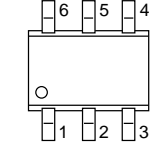
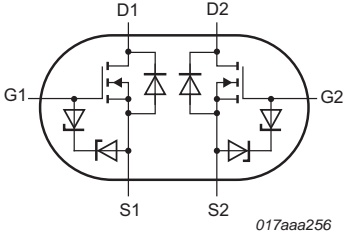
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Per transistor</b>						
$V_{DS}$	drain-source voltage	$T_j = 25\text{ °C}$	-	-	30	V
$V_{GS}$	gate-source voltage		-8	-	8	V
$I_D$	drain current	$V_{GS} = 4.5\text{ V}; T_{amb} = 25\text{ °C}$	[1]	-	350	mA
<b>Static characteristics (per transistor)</b>						
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = 4.5\text{ V}; I_D = 350\text{ mA}; T_j = 25\text{ °C}$	-	1	1.4	$\Omega$

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for drain 1 cm<sup>2</sup>.



## 2. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	S1	source TR1	 <p>SOT363 (SC-88)</p>	 <p>017aaa256</p>
2	G1	gate TR1		
3	D2	drain TR2		
4	S2	source TR2		
5	G2	gate TR2		
6	D1	drain TR1		

## 3. Ordering information

Table 3. Ordering information

Type number	Package		Version
	Name	Description	
NX3008NBKS	SC-88	plastic surface-mounted package; 6 leads	SOT363

## 4. Marking

Table 4. Marking codes

Type number	Marking code <sup>[1]</sup>
NX3008NBKS	LB%

[1] % = placeholder for manufacturing site code.

## 5. Limiting values

**Table 5. Limiting values**

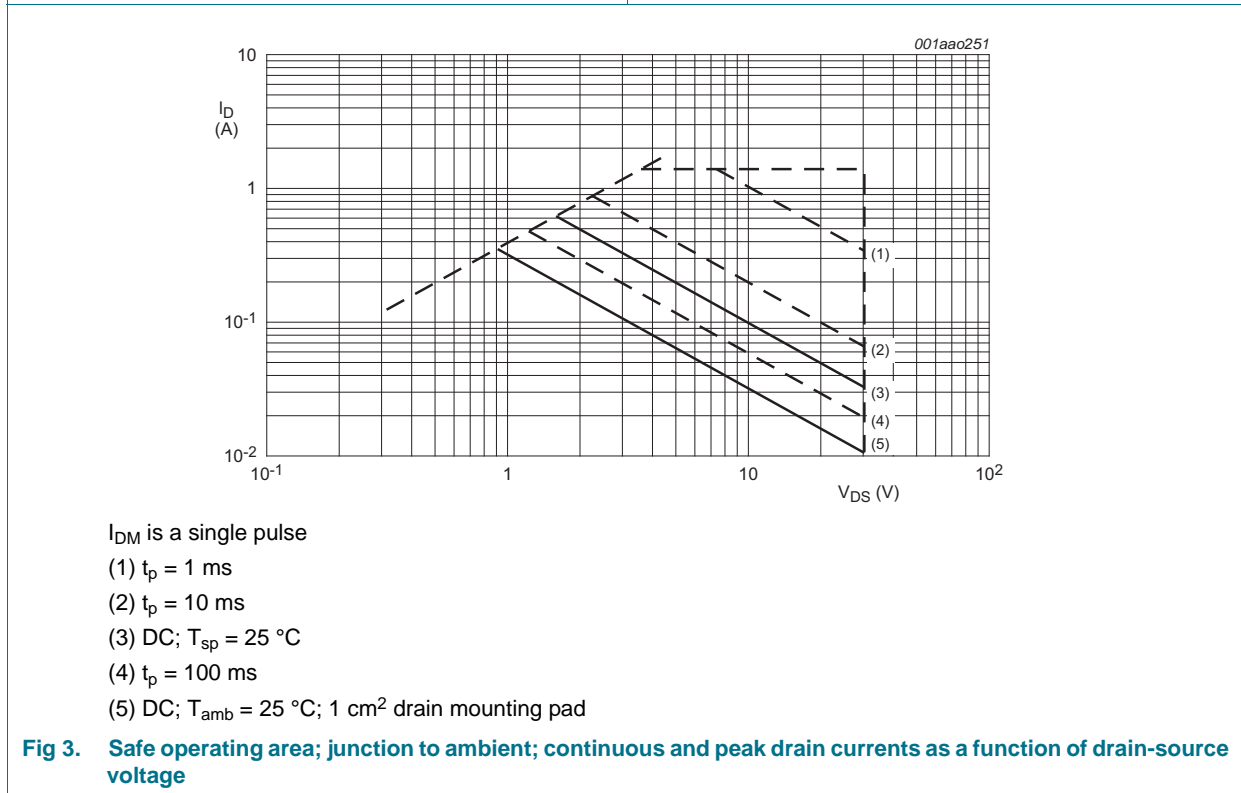
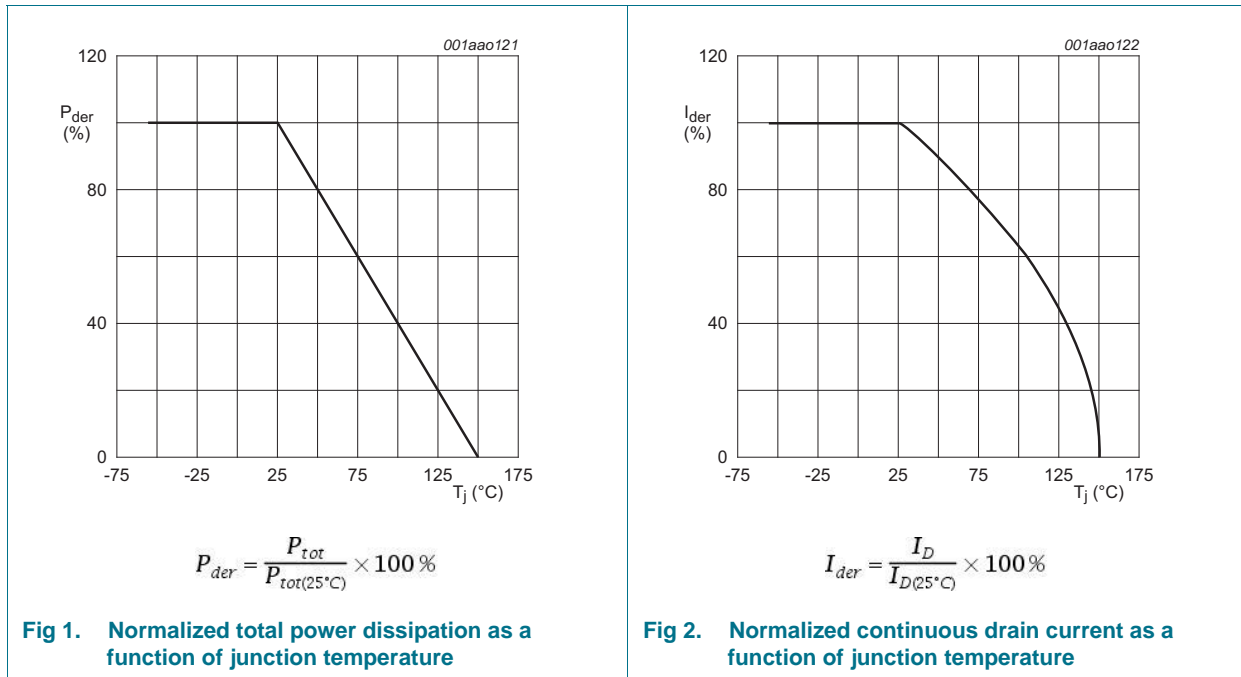
*In accordance with the Absolute Maximum Rating System (IEC 60134).*

Symbol	Parameter	Conditions	Min	Max	Unit	
<b>Per transistor</b>						
$V_{DS}$	drain-source voltage	$T_j = 25\text{ °C}$	-	30	V	
$V_{GS}$	gate-source voltage		-8	8	V	
$I_D$	drain current	$V_{GS} = 4.5\text{ V}; T_{amb} = 25\text{ °C}$	[1]	-	350	mA
		$V_{GS} = 4.5\text{ V}; T_{amb} = 100\text{ °C}$	[1]	-	230	mA
$I_{DM}$	peak drain current	$T_{amb} = 25\text{ °C};$ single pulse; $t_p \leq 10\text{ }\mu\text{s}$	-	1.4	A	
$P_{tot}$	total power dissipation	$T_{amb} = 25\text{ °C}$	[2]	-	280	mW
			[1]	-	320	mW
		$T_{sp} = 25\text{ °C}$	-	-	990	mW
<b>Per device</b>						
$P_{tot}$	total power dissipation	$T_{amb} = 25\text{ °C}$	[2]	-	445	mW
$T_j$	junction temperature		-55	150	°C	
$T_{amb}$	ambient temperature		-55	150	°C	
$T_{stg}$	storage temperature		-65	150	°C	
<b>Source-drain diode</b>						
$I_S$	source current	$T_{amb} = 25\text{ °C}$	-	300	mA	
<b>ESD maximum rating</b>						
$V_{ESD}$	electrostatic discharge voltage	HBM	[3]	-	2000	V

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for drain 1 cm<sup>2</sup>.

[2] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[3] Measured between all pins.



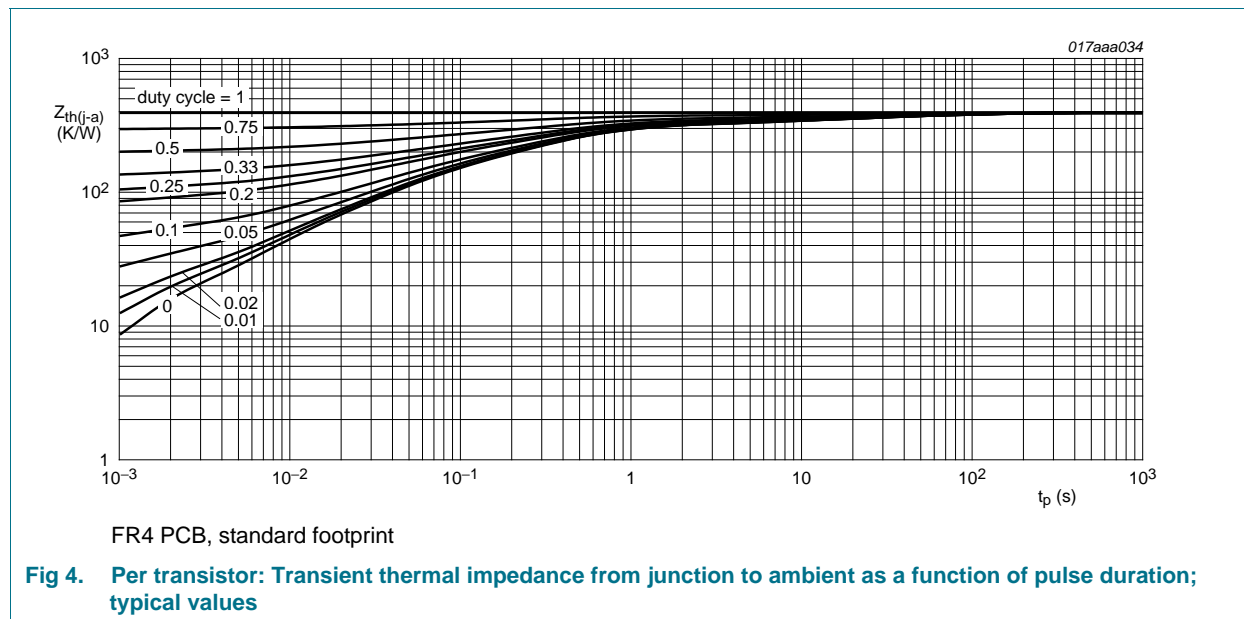
## 6. Thermal characteristics

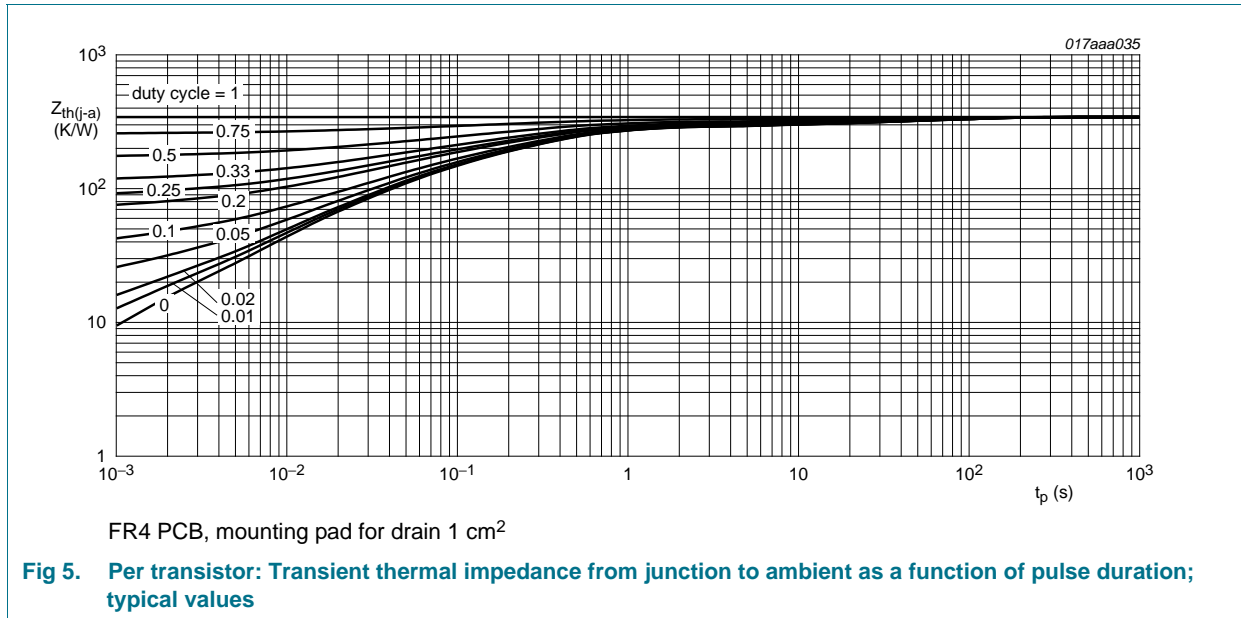
**Table 6. Thermal characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Per transistor</b>						
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	390	445 K/W
			[2]	-	340	390 K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		-	-	130	K/W
<b>Per device</b>						
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	300	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for drain 1 cm<sup>2</sup>.

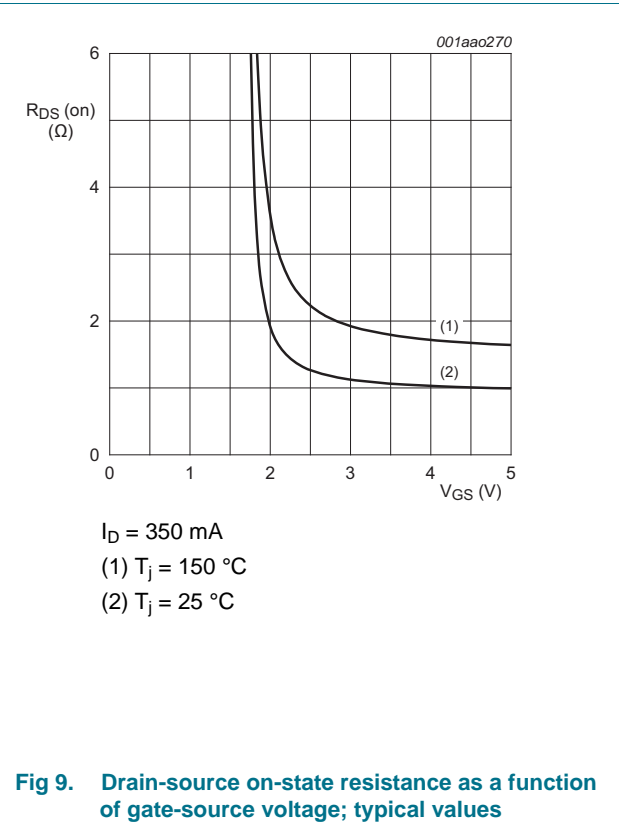
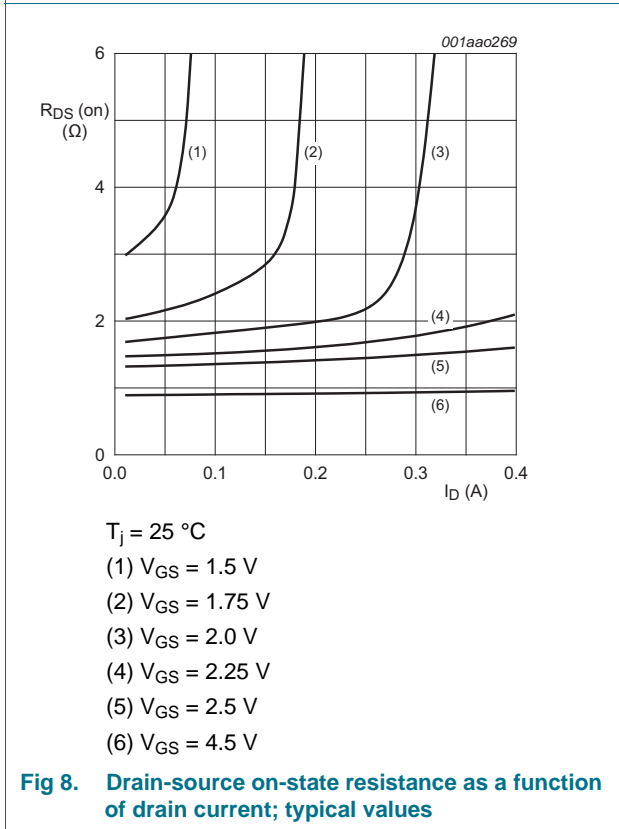
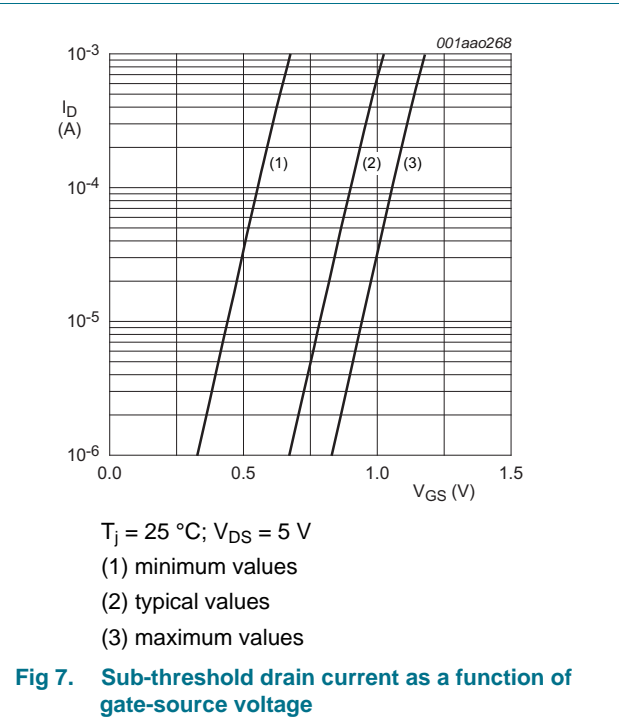
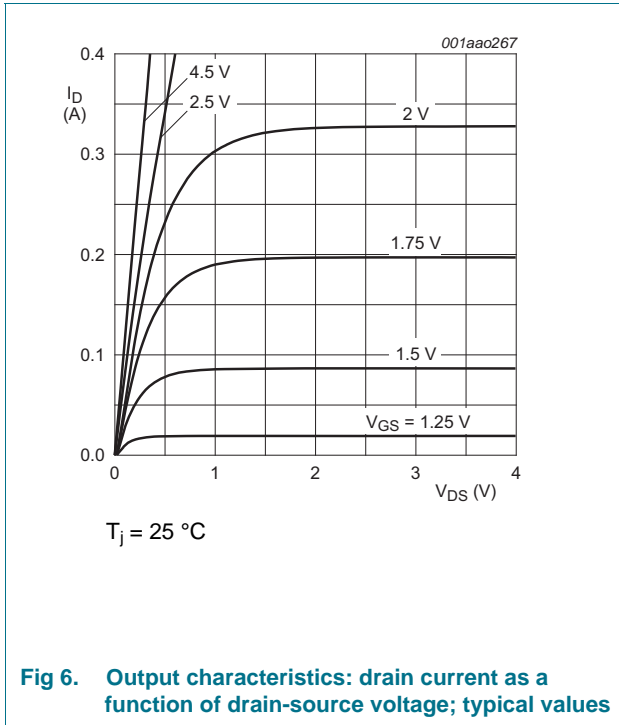




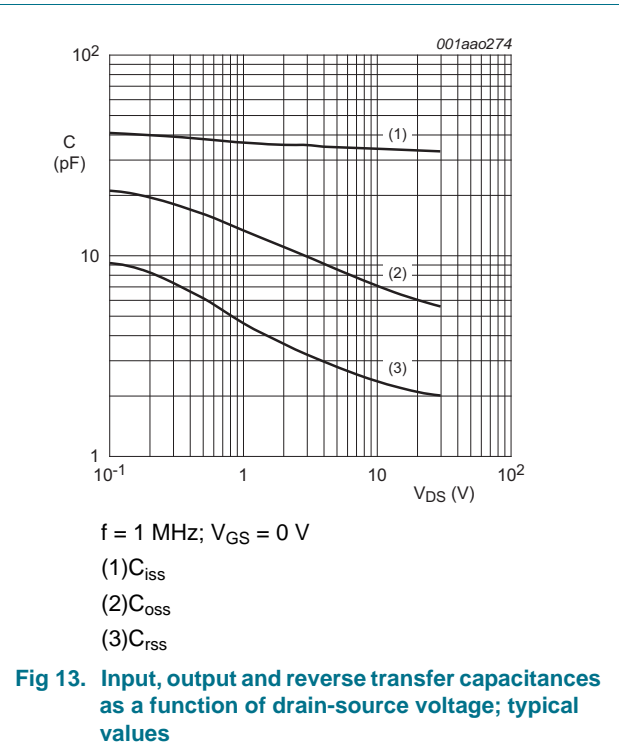
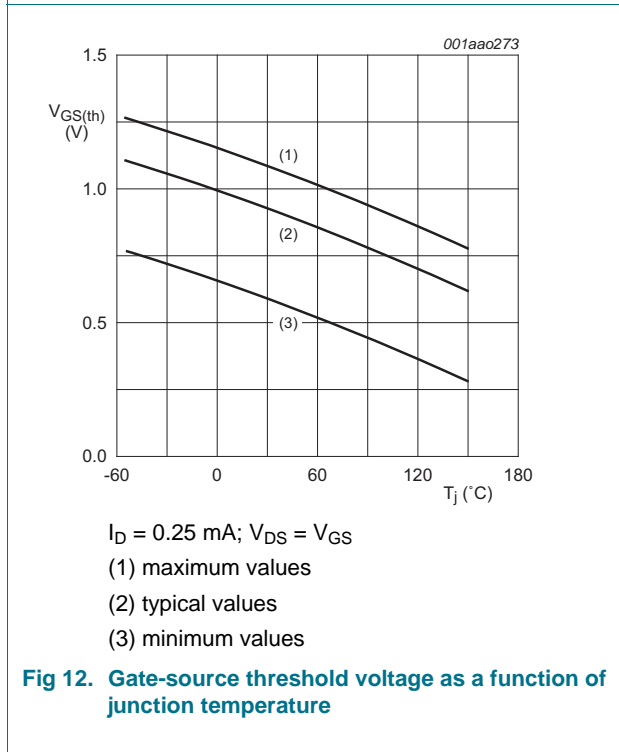
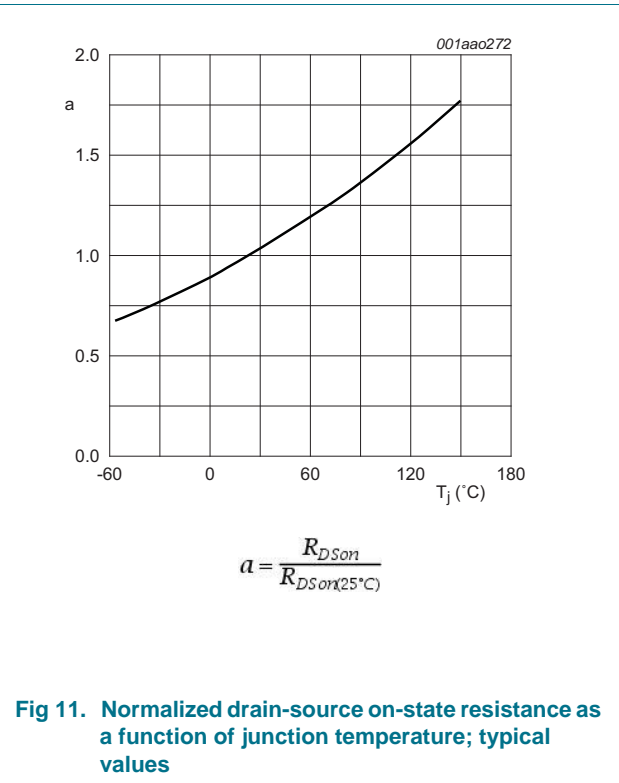
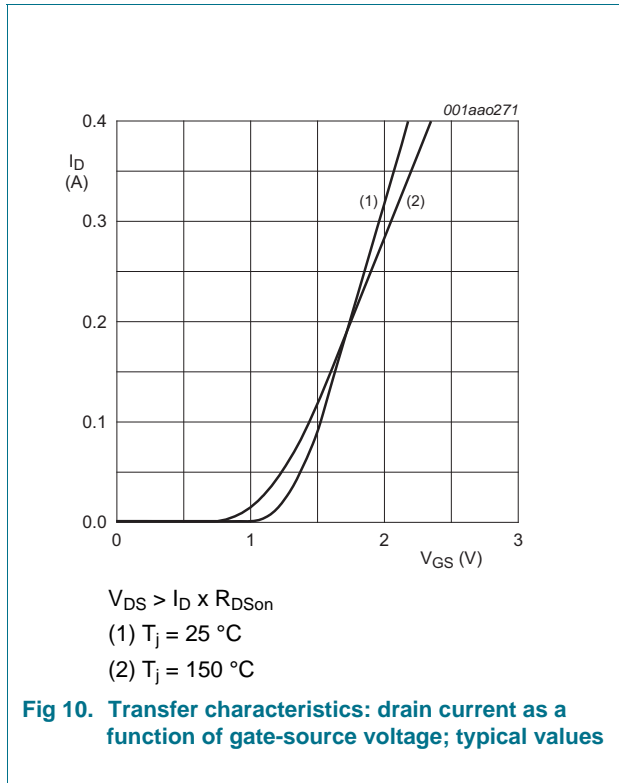
## 7. Characteristics

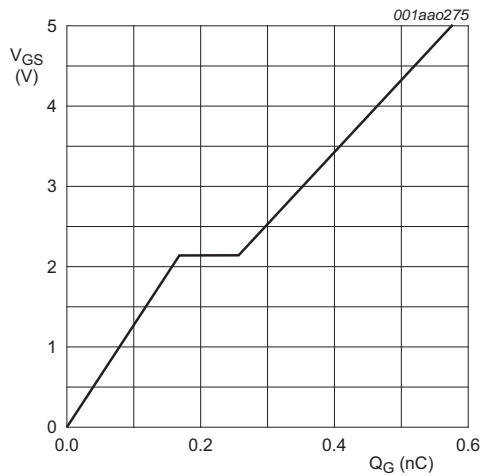
Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics (per transistor)</b>						
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = 250 \mu\text{A}$ ; $V_{GS} = 0 \text{ V}$ ; $T_j = 25 \text{ }^\circ\text{C}$	30	-	-	V
$V_{GSth}$	gate-source threshold voltage	$I_D = 250 \mu\text{A}$ ; $V_{DS} = V_{GS}$ ; $T_j = 25 \text{ }^\circ\text{C}$	0.6	0.9	1.1	V
$I_{DSS}$	drain leakage current	$V_{DS} = 30 \text{ V}$ ; $V_{GS} = 0 \text{ V}$ ; $T_j = 25 \text{ }^\circ\text{C}$	-	-	1	$\mu\text{A}$
		$V_{DS} = 30 \text{ V}$ ; $V_{GS} = 0 \text{ V}$ ; $T_j = 150 \text{ }^\circ\text{C}$	-	-	10	$\mu\text{A}$
$I_{GSS}$	gate leakage current	$V_{GS} = 8 \text{ V}$ ; $V_{DS} = 0 \text{ V}$ ; $T_j = 25 \text{ }^\circ\text{C}$	-	0.2	1	$\mu\text{A}$
		$V_{GS} = -8 \text{ V}$ ; $V_{DS} = 0 \text{ V}$ ; $T_j = 25 \text{ }^\circ\text{C}$	-	0.2	1	$\mu\text{A}$
		$V_{GS} = 4.5 \text{ V}$ ; $V_{DS} = 0 \text{ V}$ ; $T_j = 25 \text{ }^\circ\text{C}$	-	10	-	nA
		$V_{GS} = -4.5 \text{ V}$ ; $V_{DS} = 0 \text{ V}$ ; $T_j = 25 \text{ }^\circ\text{C}$	-	10	-	nA
		$V_{GS} = 2.5 \text{ V}$ ; $V_{DS} = 0 \text{ V}$ ; $T_j = 25 \text{ }^\circ\text{C}$	-	1	-	nA
		$V_{GS} = -2.5 \text{ V}$ ; $V_{DS} = 0 \text{ V}$ ; $T_j = 25 \text{ }^\circ\text{C}$	-	1	-	nA
$R_{DSon}$	drain-source on-state resistance	$V_{GS} = 4.5 \text{ V}$ ; $I_D = 350 \text{ mA}$ ; $T_j = 25 \text{ }^\circ\text{C}$	-	1	1.4	$\Omega$
		$V_{GS} = 4.5 \text{ V}$ ; $I_D = 350 \text{ mA}$ ; $T_j = 150 \text{ }^\circ\text{C}$	-	1.8	2.5	$\Omega$
		$V_{GS} = 2.5 \text{ V}$ ; $I_D = 200 \text{ mA}$ ; $T_j = 25 \text{ }^\circ\text{C}$	-	1.4	2.1	$\Omega$
		$V_{GS} = 1.8 \text{ V}$ ; $I_D = 10 \text{ mA}$ ; $T_j = 25 \text{ }^\circ\text{C}$	-	2	2.8	$\Omega$
$g_{fs}$	forward transconductance	$V_{DS} = 10 \text{ V}$ ; $I_D = 350 \text{ mA}$ ; $T_j = 25 \text{ }^\circ\text{C}$	-	310	-	mS
<b>Dynamic characteristics (per transistor)</b>						
$Q_{G(tot)}$	total gate charge	$V_{DS} = 15 \text{ V}$ ; $I_D = 350 \text{ mA}$ ; $V_{GS} = 4.5 \text{ V}$ ; $T_j = 25 \text{ }^\circ\text{C}$	-	0.52	0.68	nC
$Q_{GS}$	gate-source charge		-	0.17	-	nC
$Q_{GD}$	gate-drain charge		-	0.08	-	nC
$C_{iss}$	input capacitance	$V_{DS} = 15 \text{ V}$ ; $f = 1 \text{ MHz}$ ; $V_{GS} = 0 \text{ V}$ ; $T_j = 25 \text{ }^\circ\text{C}$	-	34	50	pF
$C_{oss}$	output capacitance		-	6.5	-	pF
$C_{rss}$	reverse transfer capacitance		-	2.2	-	pF
$t_{d(on)}$	turn-on delay time	$V_{DS} = 20 \text{ V}$ ; $R_L = 250 \Omega$ ; $V_{GS} = 4.5 \text{ V}$ ; $R_{G(ext)} = 6 \Omega$ ; $T_j = 25 \text{ }^\circ\text{C}$	-	15	30	ns
$t_r$	rise time		-	11	-	ns
$t_{d(off)}$	turn-off delay time		-	69	138	ns
$t_f$	fall time		-	19	-	ns
<b>Source-drain diode (per transistor)</b>						
$V_{SD}$	source-drain voltage	$I_S = 350 \text{ mA}$ ; $V_{GS} = 0 \text{ V}$ ; $T_j = 25 \text{ }^\circ\text{C}$	0.47	0.85	1.2	V



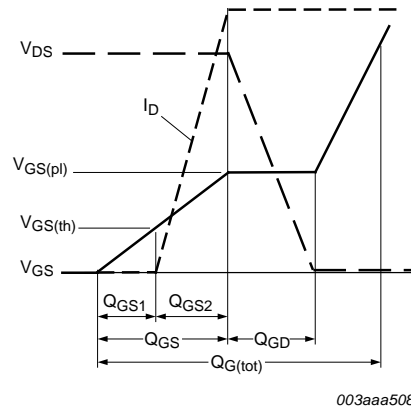




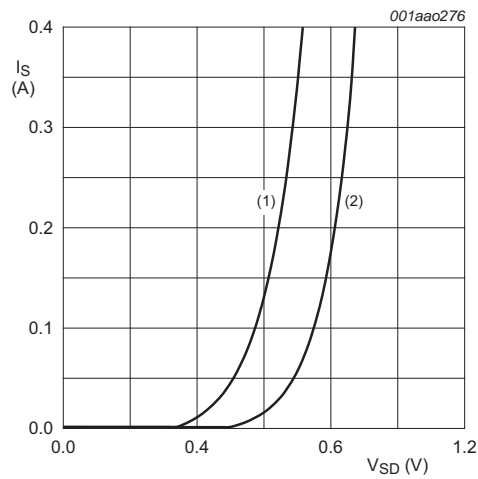


$I_D = 350$  mA;  $V_{DS} = 15$  V;  $T_{amb} = 25$  °C

**Fig 14. Gate-source voltage as a function of gate charge; typical values**



**Fig 15. Gate charge waveform definitions**



$V_{GS} = 0$  V  
 (1)  $T_j = 150$  °C  
 (2)  $T_j = 25$  °C

**Fig 16. Source current as a function of source-drain voltage; typical values**

## 8. Test information

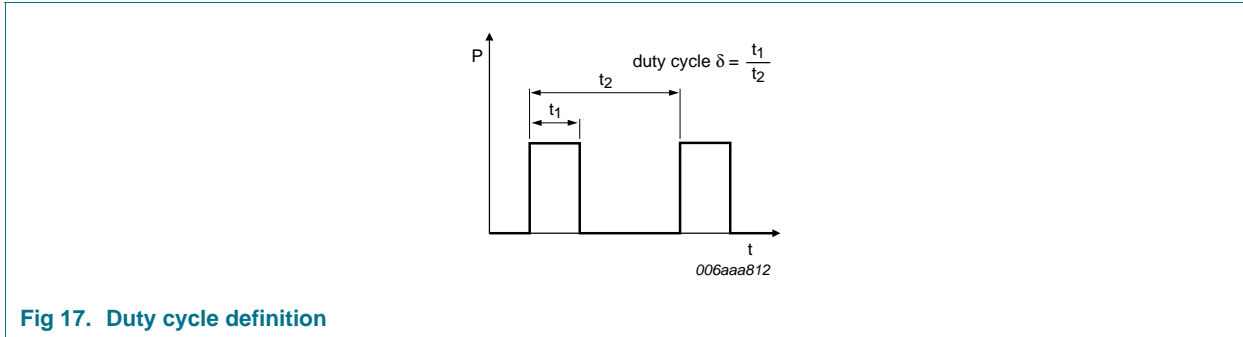


Fig 17. Duty cycle definition

### 8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - *Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

**9. Package outline**

Plastic surface-mounted package; 6 leads

SOT363

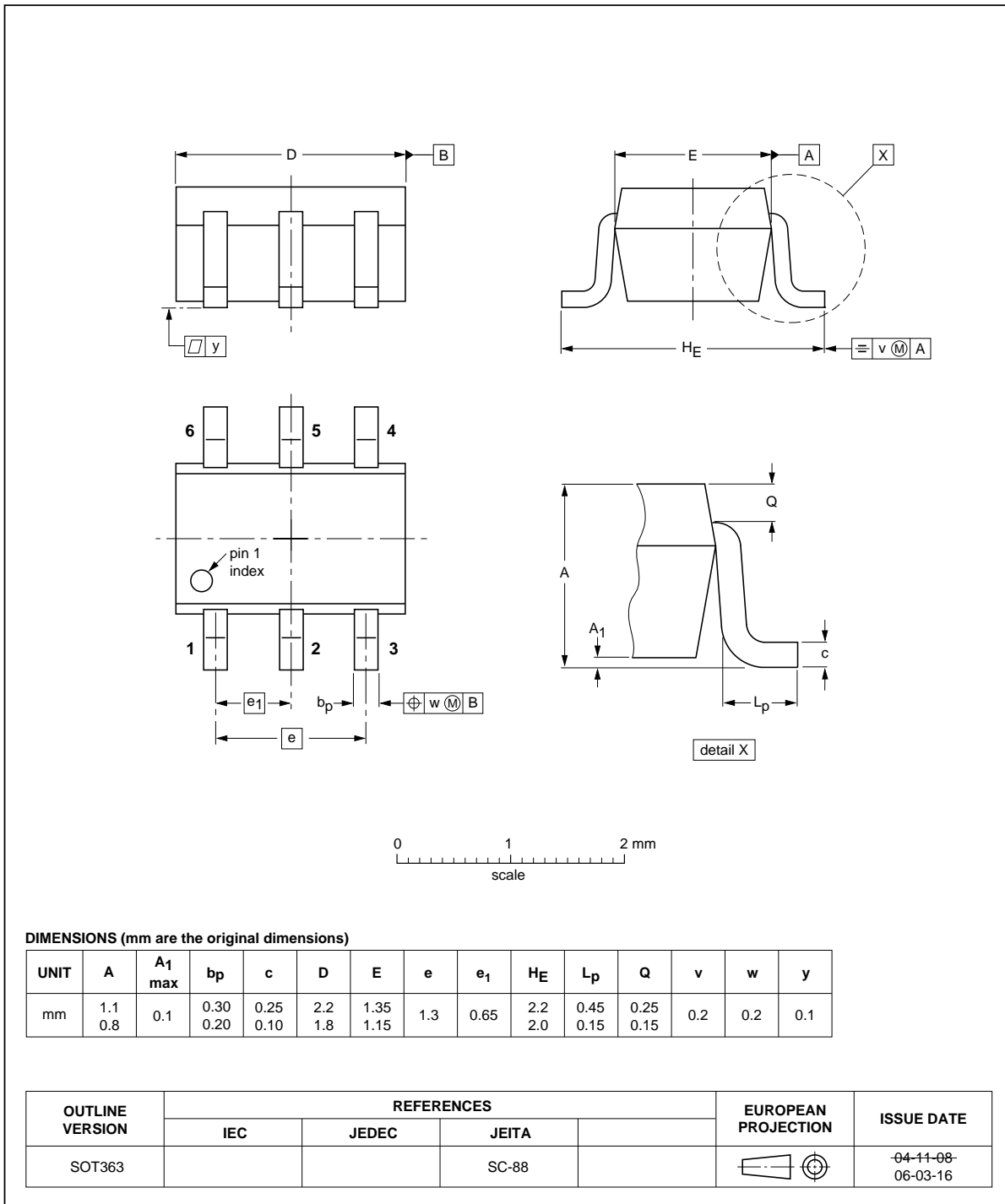
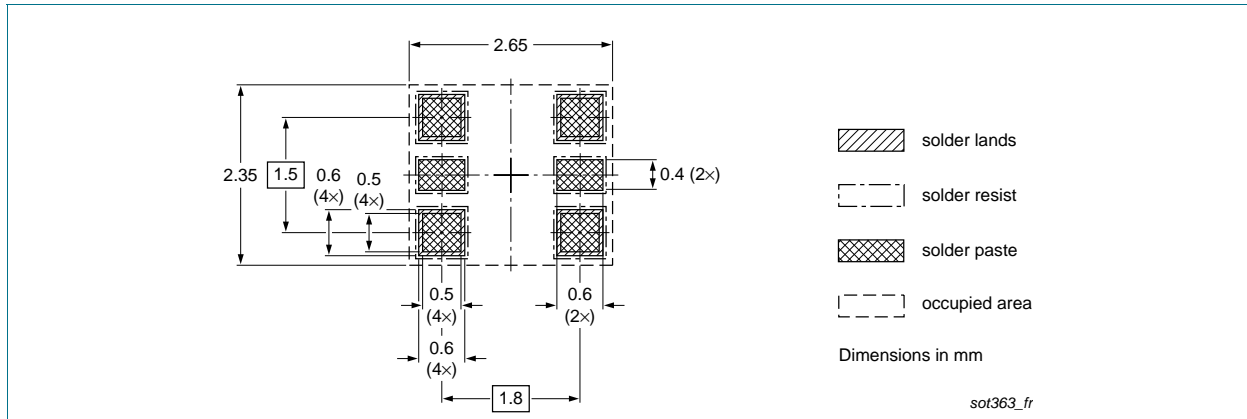
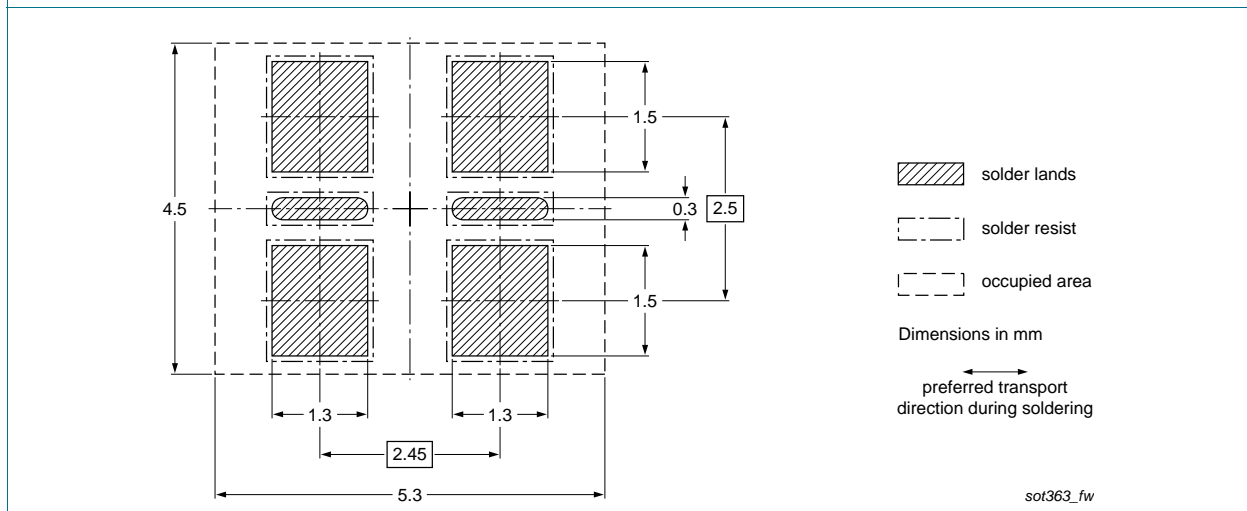


Fig 18. Package outline SOT363 (SC-88)

**10. Soldering**



**Fig 19. Reflow soldering footprint for SOT363 (SC-88)**



**Fig 20. Wave soldering footprint for SOT363 (SC-88)**

## 11. Revision history

Table 8. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
NX3008NBKS v.1	20110801	Product data sheet	-	-

## 12. Legal information

### 12.1 Data sheet status

Document status [1] [2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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